



Connector, MTA-100

1. SCOPE**1.1. Content**

This specification covers performance, tests and quality requirements for the TE Connectivity (TE) MTA-100 connector system. This system is mass terminated using insulation displacement technology on 0.100 inch centerlines and mates with 0.025 inch square posts providing a reliable interconnection between wires and posts mounted on printed circuit boards. The standard system is available in 2 through 28 positions. The MTA-100 connector system is designed to be terminated to 28 AWG to 22 AWG wire, tin plated UL style 1007, 1061 or wire which specifies PVC insulation with temperature rating compatible with specified operating temperatures, see Figure 4. Wire shall meet application requirements specified in Application Specification 114-1019. Insulation diameters are: 0.050 inch maximum outside diameter for mass termination and 0.060 inch maximum outside diameter for single termination.

1.2. Qualification

When tests are performed on the subject product line, procedures specified in Figure 1 shall be used. All inspections shall be performed using the applicable inspection plan and product drawing.

1.3. Qualification Test Results

Successful qualification testing on the subject product line was completed between 08Aug96 to 20Jan97 and on 08Jan16. The Qualification Test Report number for this testing is 501-366.

1.4. Revision Summary

Revisions to this specification include:

- Updated mating force requirement in Figure 1.
- Updated format to corporate requirements, including new logo and addition of Section 4 and Paragraphs 1.3, 1.4, and 3.4.

2. APPLICABLE DOCUMENTS AND FORMS

The following documents form a part of this specification to the extent specified herein. Unless otherwise specified, the latest edition of the document applies. In the event of conflict between the requirements of this specification and the product drawing, the product drawing shall take precedence. In the event of conflict between the requirements of this specification and the referenced documents, this specification shall take precedence.

2.1. TE Connectivity Specifications

114-1019	Application Specification
501-366	Qualification Test Report

2.2. Reference Documents

109-1	General Requirements for Testing
109 Series	Test Specifications as indicated in Figure 1

3. REQUIREMENTS**3.1. Design and Construction**

Product shall be of the design, construction, materials and physical dimensions specified on the applicable product drawing.

3.2. Materials

Materials used in the construction of this product shall be as specified on the applicable TE drawing.

- A. Contact: Phosphor bronze, tin or tin-lead plating and gold over nickel plating
- B. Header: Thermoplastic polyester, UL 94V-0
- C. Housing: Nylon 6/6 or Nylon 6/12, UL 94V-2 and UL 94V-0
- D. Posts, header: Phosphor bronze, tin plating and gold over nickel plating

3.3. Ratings

- A. Voltage Rating: 250 VAC
- B. Current Rating: See Figure 4 for applicable current carrying capability
- C. Temperature Rating: -55°C to +105°C

3.4. Performance Requirements and Test Description

The product should meet the electrical, mechanical and environmental performance requirements specified in Figure 1. All tests shall be performed at ambient environmental conditions otherwise specified.

3.5. Test Requirements and Procedure Summary

Test Description	Requirement		Procedure
Examination of product	Meets requirements of product drawing and Application Spec 114-1019		Visual, dimensional and functional per applicable quality inspection plan
Electrical			
Termination resistance	6 milliohms maximum initial. ΔR 10 milliohms maximum		TE 109-6-1. Subject mated contacts assembled in housing to 50 mv maximum open circuit at 100 ma maximum. See Figures 3 and 5
Insulation resistance	5000 megohms minimum initial		TE Spec 109-28-4. Test between adjacent contacts of unmated samples
Dielectric withstanding voltage	750 vac at sea level. 1 minute hold with no breakdown or flashover		TE Spec 109-29-1. Test between adjacent contacts of unmated samples
Temperature rise vs current	30°C maximum temperature rise at specified current		TE Spec 109-45-2. Measure temperature rise vs current. See Figures 4 and 5
Mechanical			
Solderability	Solderable area shall have minimum of 95% solder coverage		TE Spec 109-11-2. Subject contacts to solderability
Termination tensile strength, parallel, unmated	Wire Size (AWG)	Slot Tensile (Pounds, minimum)	TE Spec 109-16. Determine slot tensile at maximum rate of 1 inch per minute. Pull parallel to terminated wire. See Figure 6
	28	4	
	24	5	
	22	12	

Figure 1 (continued)

Termination tensile strength, perpendicular, unmated	Wire Size (AWG)	Slot Tensile (Pounds, minimum)	TE Spec 109-16. Determine slot tensile at maximum rate of 1 inch per minute. Pull perpendicular to terminated wire. See Figure 6
	28	1	
	24	1	
	22	3	
Vibration, sinusoidal	No discontinuities of 1 microsecond or longer duration. See Note		TE Spec 109-21-1. Subject mated samples to 10-55-10 Hz traversed in 1 minute at 0.06 inch total excursion. 2 hours in each of 3 mutually perpendicular planes
Physical shock	No discontinuities of 1 microsecond or longer duration. See Note		TE Spec 109-26-1. Subject mated samples to 50 G's halfsine shock pulses of 11 milliseconds duration. 3 shocks in each direction applied along 3 mutually perpendicular planes, 18 total shocks
Durability	See Note		TE Spec 109-27. Manually mate and unmate samples with friction lock header for 25 cycles
Mating force	2.4 pounds maximum average per contact		TE Spec 109-42, Condition A. Measure force necessary to mate samples with friction lock header from point of initial contact to depth of 0.200 inch at maximum rate of 0.5 inch per minute
Unmating force	0.8 pound minimum average per contact		TE Spec 109-42, Condition A. Measure force necessary to unmate samples from friction lock header at maximum rate of 0.5 inch per minute
Post Retention Force	3 pound minimum average per contact		TE Spec 109-30 Measure post retention force at maximum rate of 0.5 inch per minute
Environmental			
Thermal shock	See Note		TE Spec 109-22. Subject mated samples to 25 cycles between -55 and 105°C
Humidity-temperature cycling	See Note		AMP Spec 109-23-3, Condition B. Subject mated samples to 10 cycles between 25 and 65°C at 95% RH
Temperature life	See Note		AMP Spec 109-43. Subject mated samples to temperature life at 85°C for 1000 hours
Mixed flowing gas	See Note		AMP Spec 109-85-3. Subject mated samples to environmental class III for 20 days
Resistance to soldering heat	See Note		TE Spec 109-202, Condition C. The solder bath temperature shall be maintained at 260 +0/-5°C. The hold time in the solder shall be 5 +2/-0 seconds

Figure 1 (end)


NOTE

Shall meet visual requirements, show no physical damage, and meet requirements of additional tests as specified in the Product Qualification and Requalification Test Sequence Figure 2.

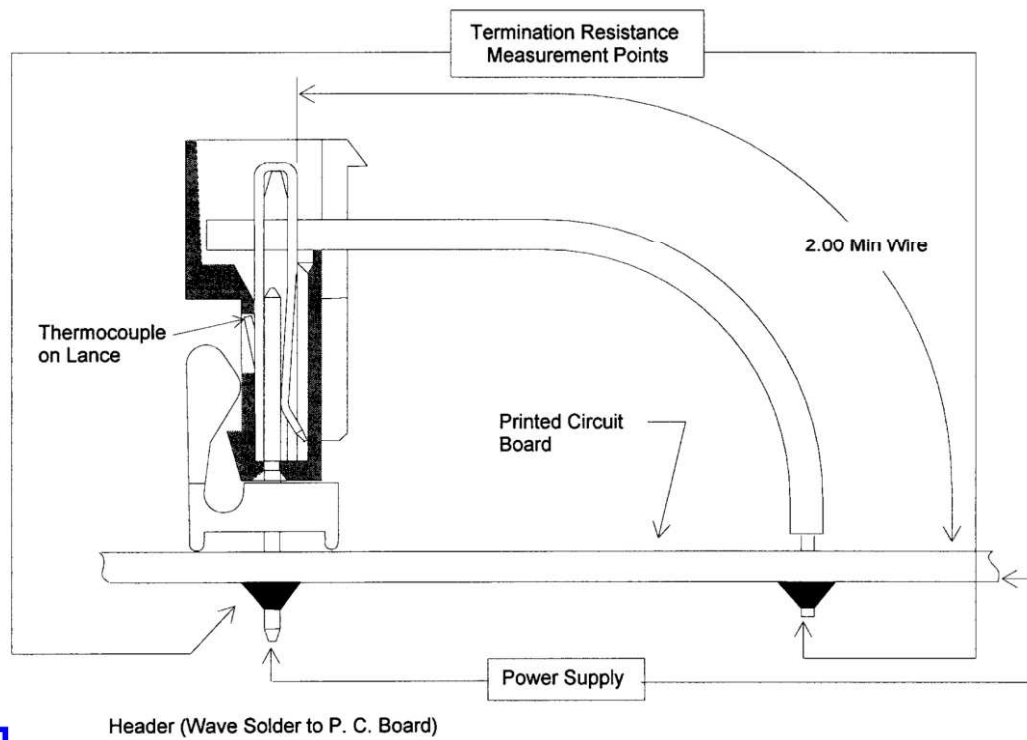
3.6. Product Qualification and Requalification Test Sequence

TEST OR EXAMINATION	TEST GROUP (a)							
	1	2(c)	3(d)	4	5	6	7	8
	TEST SEQUENCE (b)							
Examination of product	1, 9	1,9	1,5	1,8	1,3	1,3	1,3	1,3
Termination resistance	3, 7	2,7	2,4					
Insulation resistance				2,6				
Dielectric withstanding voltage				3,7				
Temperature rise vs current		3,8						
Solderability						2		
Termination tensile strength					2(f)			
Vibration	5	6(e)						
Physical shock	6							
Durability	4							
Mating force	2							
Unmating force	8							
Post retention force							2	
Thermal shock				4				
Humidity-temperature cycling		4(g)		5				
Temperature life		5						
Mixed flowing gas			3(g)					
Resistance to soldering heat								2

Figure 2

NOTE

- (a) Samples shall be prepared in accordance with applicable Instruction Sheets and shall be selected at random from current production. Test group 1 shall consist of 5, 6 position standard tin-lead plated samples and 5, 6 position gold plated samples. All samples shall be terminated to the maximum wire size and mounted on printed circuit board PN 93-660017 (see Figure 5). Test group 2 shall consist of 3, 10 position standard tin-lead plated samples terminated to 28 AWG wire and mounted on printed circuit board PN 93-660652; and 3, 10 position standard tin-lead plated samples terminated to 22 AWG wire and mounted on printed circuit board PN 93-660651 (see Figure 5). Test group 3 shall consist of 3, 10 position gold plated samples terminated to 22 AWG wire and mounted on printed circuit board PN 93-660017. Test group 4 shall consist of 5 unmounted 24 position standard tin-lead plated samples terminated to the maximum wire size. Test group 5 shall consist of 6, 10 position standard tin-lead plated samples terminated to 28 AWG wire; 6, 10 position standard tin-lead plated samples terminated to 24 AWG wire; and 6, 10 position standard tin-lead plated samples terminated to 22 AWG wire. All samples shall be unmated and unmounted. Test group 6 shall consist of 5, 6 position 0.100 inch friction lock tin-lead plated headers.
- (b) Numbers indicate sequence in which tests are performed.
- (c) Tin-lead plated samples.
- (d) Gold plated samples.
- (e) Discontinuities shall not be measured. Energize at 18°C level for 100% loadings per Test Specification 109-151.
- (f) Subject half the samples to the parallel tensile test and the remaining half to the perpendicular tensile test.
- (g) Precondition samples with 5 cycles durability



- (a) Termination resistance equals millivolts divided by test current less resistance of 2 inches of wire.
- (b) After wave soldering, the boards and posts shall be cleaned to remove all flux and contaminates.

Figure 3: Temperature and Termination Resistance Measurement Points

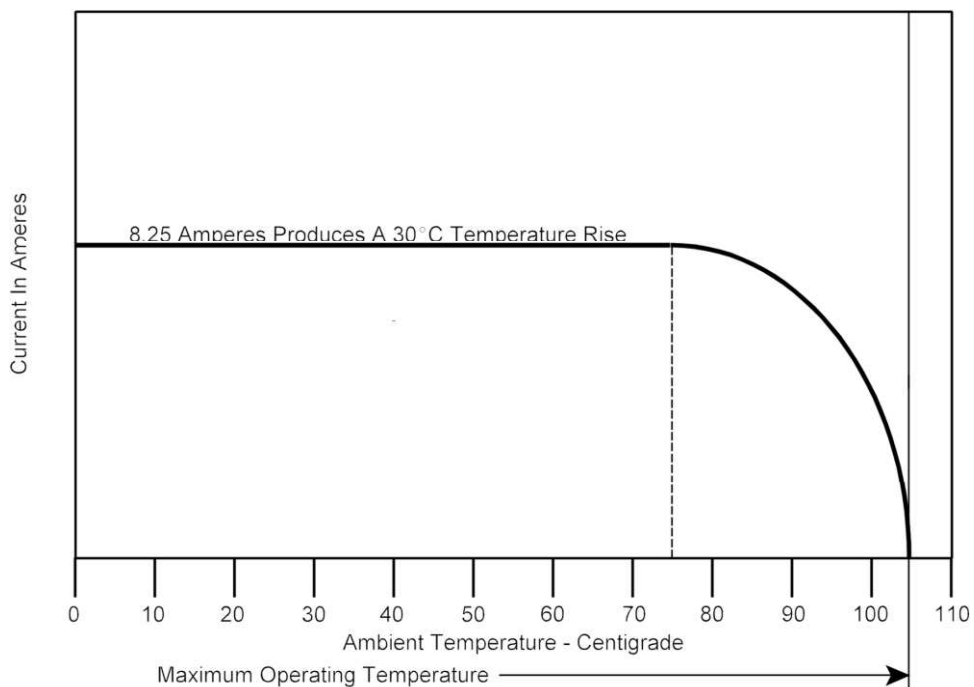


Figure 4A: Current Carrying Capacity

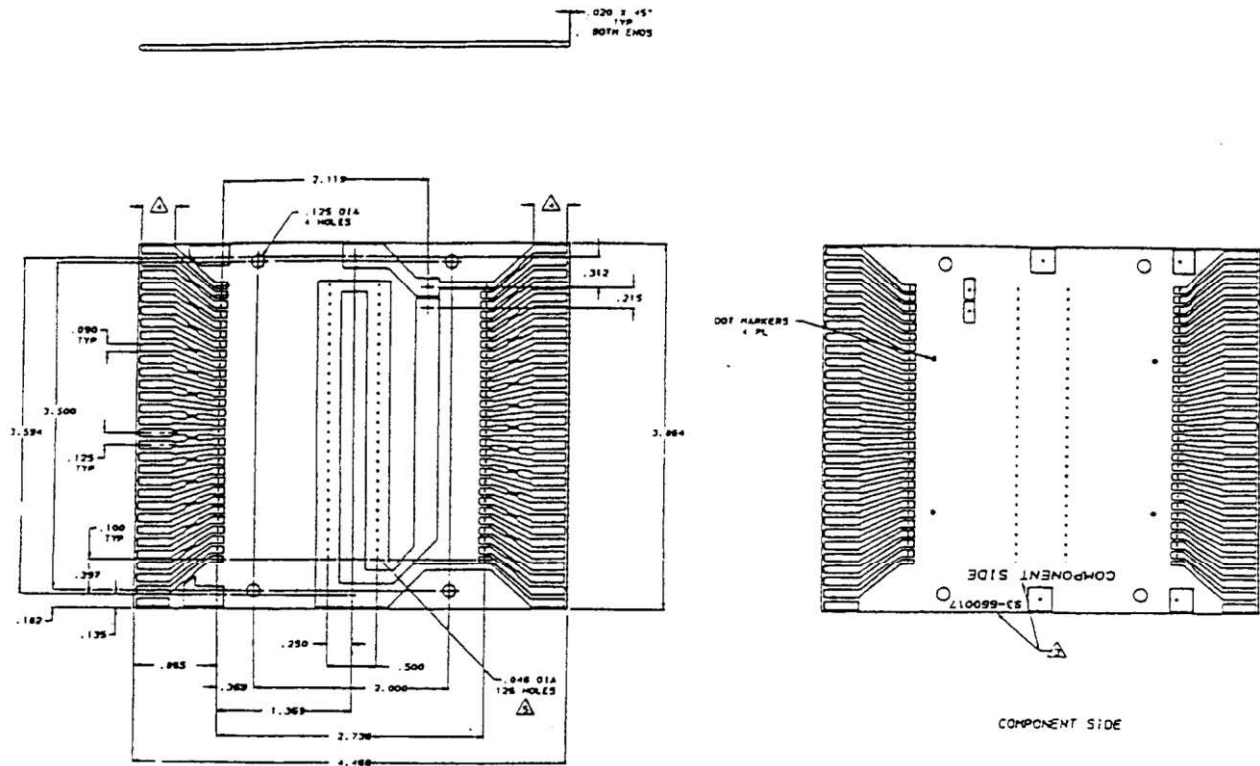
Percent Connector Loading (10 position In-Line connector)	Wire Size AWG			
	28	26	24	22
Single Contact	0.6	0.7	0.9	1
50	0.5	0.6	0.7	0.8
100	0.3	0.4	0.4	0.5



NOTE

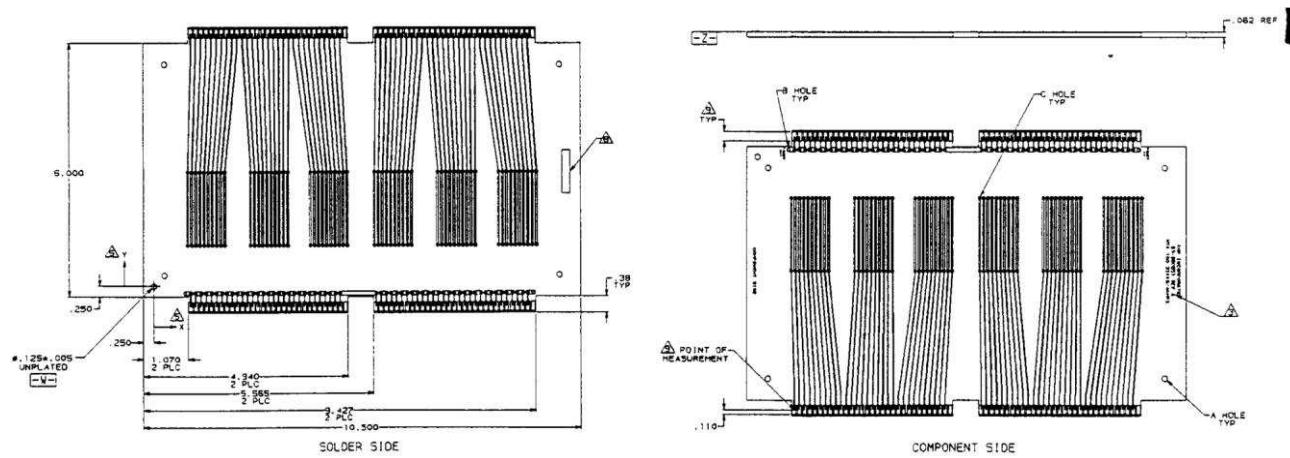
To determine acceptable current carrying capacity for percentage connector loading and wire gage indicated, use the Multiplication Factor (F) from the above chart and multiply it times the Base Rated Current for a single circuit at maximum ambient operating temperature as shown in Figure 4A.

Figure 4B



CIRCUIT SIDE

PC Board Used for Termination Resistance Dry Circuit



PC Board Used for Current Rating

Figure 5: Printed Circuit Test Boards

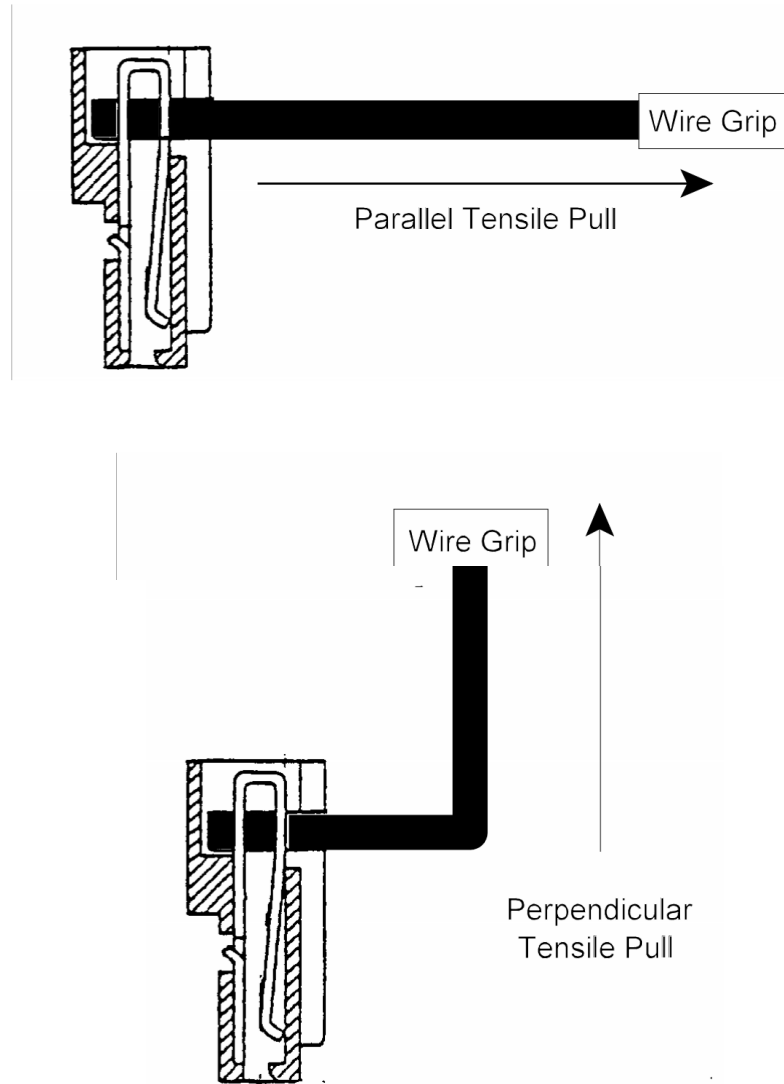


Figure 6: Termination Tensile Strength

4. QUALITY ASSURANCE PROVISIONS

4.1. Test Conditions

Unless otherwise specified, all the tests shall be performed in any combination of the following test conditions shown in Figure 7.

Temperature	15°C – 35°C
Relative Humidity	45% – 75%
Atmospheric Pressure	86.6 – 106.6 kPa

Figure 7

4.2. Qualification Testing

A. Specimen Selection

Specimens shall be prepared in accordance with applicable instruction sheets and shall be selected at random from current production. See note in Figure 2.

B. Test Sequence

Qualification inspection shall be verified by testing specimens as specified in Figure 2.

4.3. Requalification Testing

If changes significantly affecting form, fit or function are made to the product or manufacturing process, product assurance shall coordinate requalification testing, consisting of all or part of the original testing sequence as determined by development/product, quality and reliability engineering.

4.4. Acceptance

Acceptance is based on verification that the product meets the requirements in Figure 1. Failures attributed to equipment, test setup or operator deficiencies shall not disqualify the product. If product failure occurs, corrective action shall be taken and specimens resubmitted for qualification. Testing to confirm corrective action is required before resubmittal.

4.5. Quality Conformance Inspection

The applicable quality inspection plan shall specify the sampling acceptable quality level to be used. Dimensional and functional requirements shall be in accordance with the applicable product drawing and this specification.